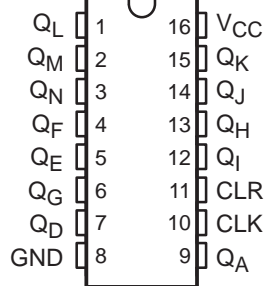


SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

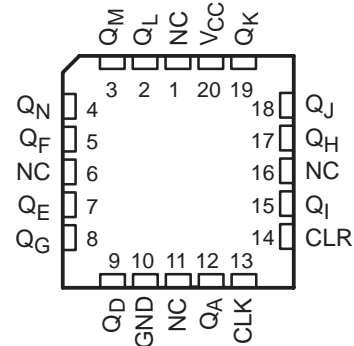
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 12$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

SN54HC4020 . . . J OR W PACKAGE
SN74HC4020 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC4020 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC4020 devices are 14-stage binary ripple-carry counters that advance on the negative-going edge of the clock pulse. The counters are reset to zero (all outputs low) independently of the clock (CLK) input when the clear (CLR) input goes high.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC4020N	SN74HC4020N
	SOIC – D	Tube of 40	SN74HC4020D	HC4020
		Reel of 2500	SN74HC4020DR	
		Reel of 250	SN74HC4020DT	
	SOP – NS	Reel of 2000	SN74HC4020NSR	HC4020
	SSOP – DB	Reel of 2000	SN74HC4020DBR	HC4020
	TSSOP – PW	Tube of 90	SN74HC4020PW	HC4020
Reel of 2000		SN74HC4020PWR		
Reel of 250		SN74HC4020PWT		
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC4020J	SNJ54HC4020J
	CFP – W	Tube of 150	SNJ54HC4020W	SNJ54HC4020W
	LCCC – FK	Tube of 55	SNJ54HC4020FK	SNJ54HC4020FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
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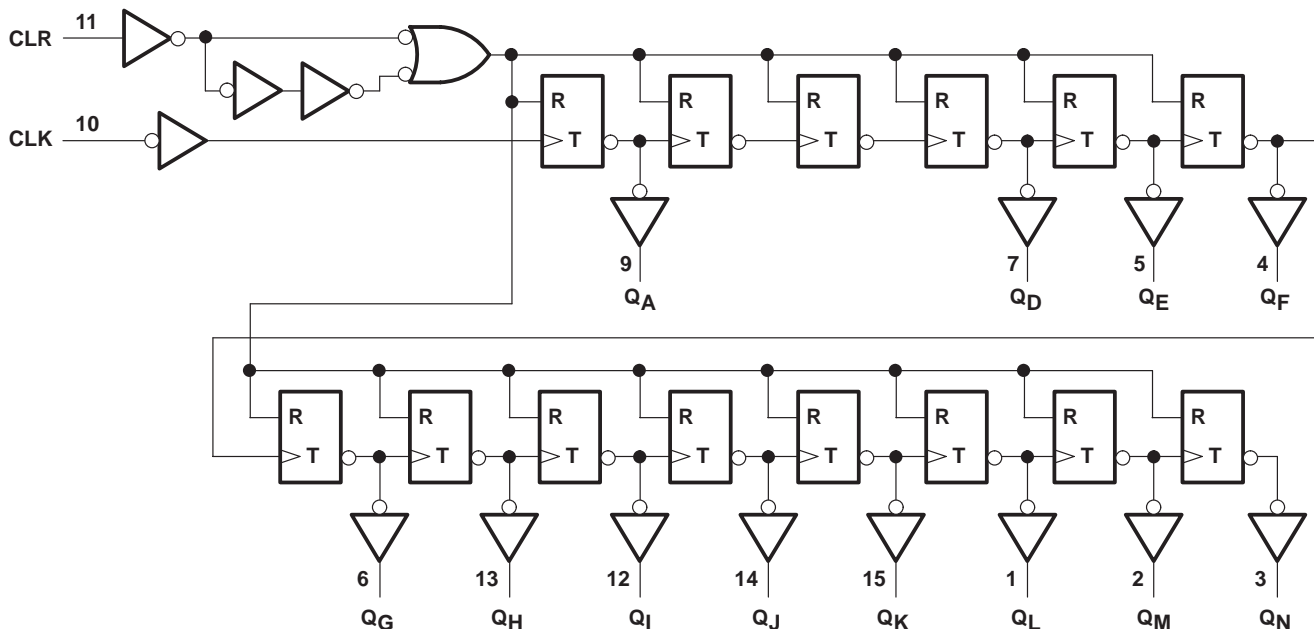
SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E – DECEMBER 1982 – REVISED SEPTEMBER 2003

FUNCTION TABLE
(each buffer)

INPUTS		FUNCTION
CLK	CLR	
↑	L	No change
↓	L	Advance to next stage
X	H	All outputs L

Logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	73°C/W
DB package	82°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54HC4020, SN74HC4020

14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E – DECEMBER 1982 – REVISED SEPTEMBER 2003

recommended operating conditions (see Note 3)

		SN54HC4020			SN74HC4020			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V		1.5	1.5		V	
		V _{CC} = 4.5 V		3.15	3.15			
		V _{CC} = 6 V		4.2	4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V			0.5		V	
		V _{CC} = 4.5 V			1.35			
		V _{CC} = 6 V			1.8			
V _I	Input voltage	0		V _{CC}	0		V _{CC}	V
V _O	Output voltage	0		V _{CC}	0		V _{CC}	V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V			1000		ns	
		V _{CC} = 4.5 V			500			
		V _{CC} = 6 V			400			
T _A	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC4020		SN74HC4020		UNIT	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX		
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998		1.9		1.9	V		
			4.5 V	4.4	4.499		4.4		4.4			
			6 V	5.9	5.999		5.9		5.9			
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84			
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34			
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		V		
			4.5 V		0.001	0.1		0.1			0.1	
			6 V		0.001	0.1		0.1			0.1	
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4			0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4			0.33	
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA	
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V				8		160		80	μA
C _i			2 V to 6 V		3	10		10		10		pF



SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E – DECEMBER 1982 – REVISED SEPTEMBER 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC4020		SN74HC4020		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V	5.5		3.7		4.3		MHz
		4.5 V	28		19		22		
		6 V	33		22		25		
t _w	Pulse duration	CLK high or low	2 V	90	135		115		ns
			4.5 V	18	27		23		
			6 V	15	23		20		
	CLR high	2 V	70	105		90			
		4.5 V	14	21		18			
		6 V	12	18		25			
t _{su}	Setup time, CLR inactive before CLK↓	2 V	60	90		75		ns	
		4.5 V	12	18		15			
		6 V	10	15		13			

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

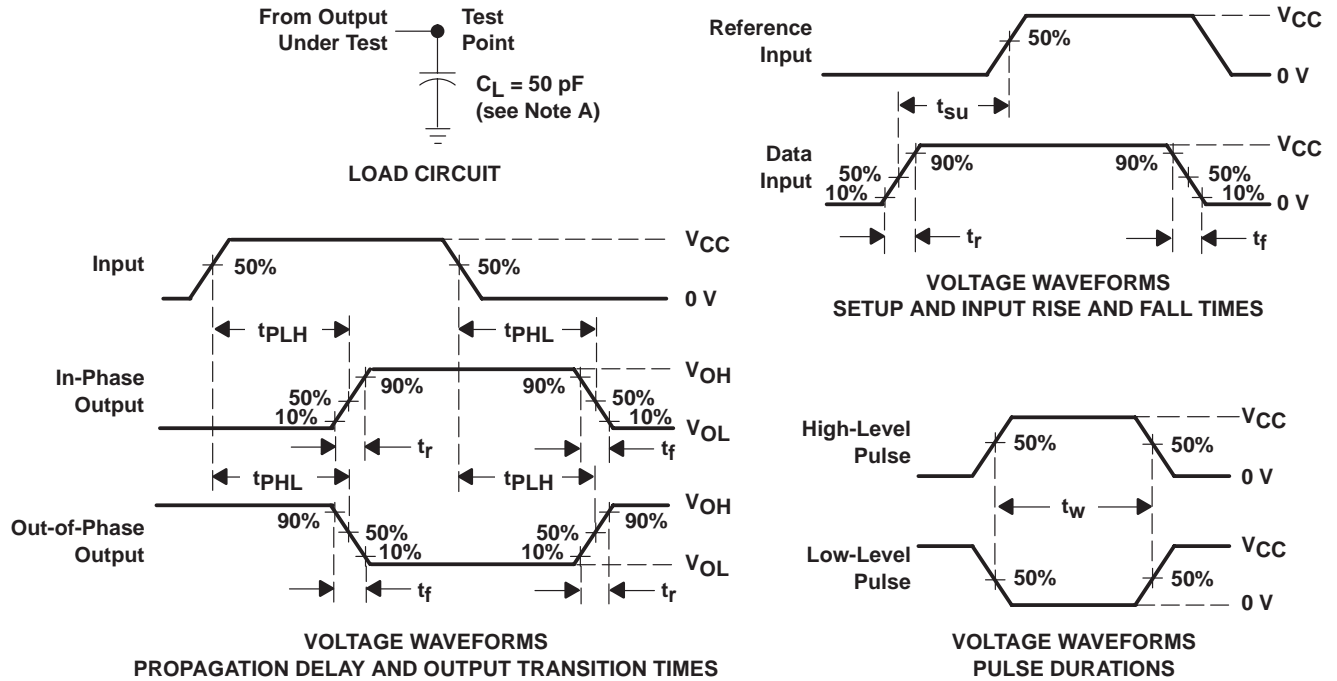
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC4020		SN74HC4020		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			2 V	5.5	10		3.7		4.3	MHz	
			4.5 V	28	45		19		22		
			6 V	33	53		22		25		
t _{pd}	CLK	Q _A	2 V		62	150		225		190	ns
			4.5 V		16	30		45		38	
			6 V		12	26		38		32	
t _{PHL}	CLR	Any	2 V		63	140		210		175	ns
			4.5 V		17	28		42		35	
			6 V		13	24		36		30	
t _t		Any	2 V		28	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load	88	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
85003012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8500301EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
8500301FA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
SN54HC4020J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN74HC4020D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4020DBR	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4020DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4020DT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4020N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC4020N3	OBSOLETE	PDIP	N	16		None	Call TI	Call TI
SN74HC4020NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC4020PW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC4020PWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC4020PWT	ACTIVE	TSSOP	PW	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC4020FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC4020J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SNJ54HC4020W	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

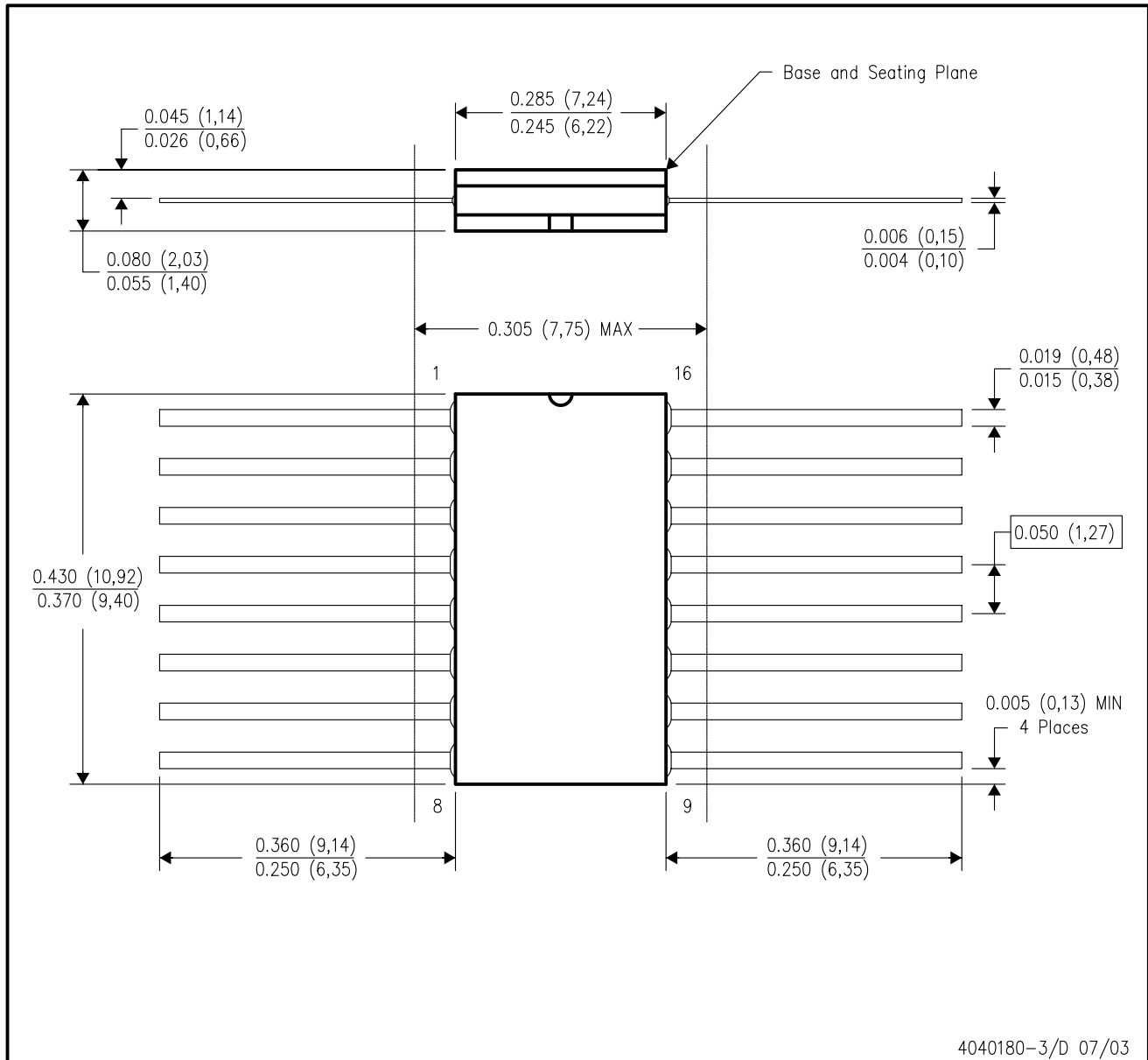
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W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

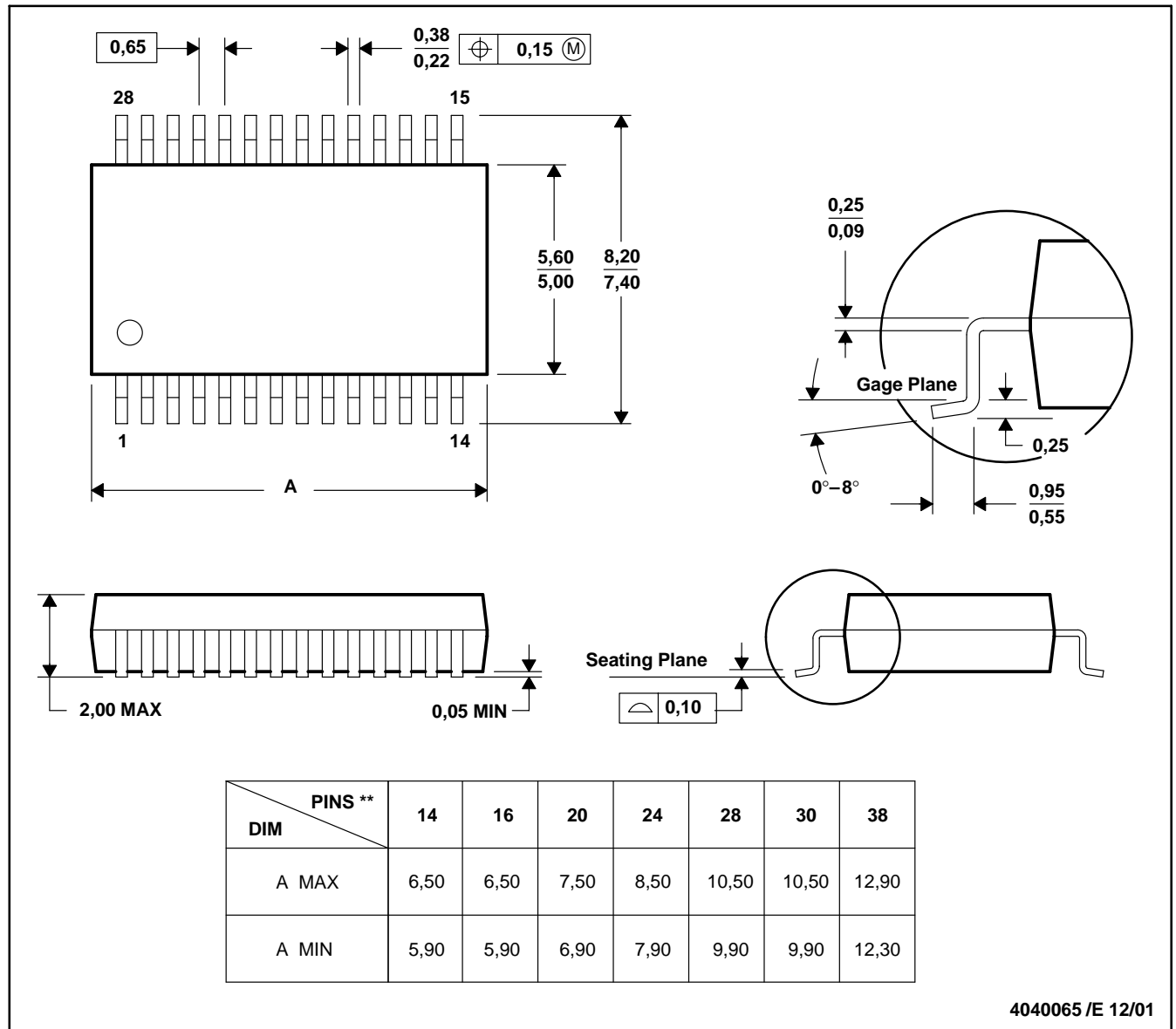


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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